IPC  ASSOCIATION CONNECT ELECTRONICS INDUSTRI	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			ler both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type * Distribute	k	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information			
upplier Infor	mation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
onsemi											2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*			Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			]	NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item	Number	Tumber Mfr Item Name			Effective Date	Version	M	Manufacturing Site	Weig	ht*	UOM	Unit Type
	FSB50550ASE		0ASE	SPM5 V2 INV 500V 1.4ohm			2023-06-08 CPA		3355	.2	mg	Each		
lanufacturing	g Proccess Informat	ion										ı		
Terminal Plating / Grid Array Material Terminal Base Alloy J-S			STD-020 MSL	Rating	Peak Proce	ess Body T	emperatur	e Max Time at Peak	Temperature	Numbe	er of Reflow Cyc	les		
Matte 7	Γin (Sn) - annealed	C	U Alloy	3			260		C	30	seconds	3		
omments														
TTENTION: MS	SL 3 Rated item requires	Bake and D	ry Pack (afte	er electrical test)										
or more informa	tion regarding material o	composition p	olease refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaalian agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Condition										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	24.0	mg	Supplier	Silicon (Si)	7440-21-3		24	mg
Die Attach	6.0	mg	Supplier	Silver (Ag)	7440-22-4		4.56	mg
			Supplier	Phenolic Resin-2	54208-63-8		1.44	mg
Die Attach Solder	4.8	mg	Supplier	Silver (Ag)	7440-22-4		0.12	mg
			A	Lead (Pb)	7439-92-1	7a	4.44	mg
			Supplier	Tin (Sn)	7440-31-5		0.24	mg
Lead Frame	1370.0	mg	Supplier	Silver (Ag)	7440-22-4		20.002	mg
			В	Nickel (Ni)	7440-02-0		30.003	mg
			Supplier	Iron (Fe)	7439-89-6		1.37	mg
			Supplier	Copper (Cu)	7440-50-8		1318.214	mg
			Supplier	Phosphorus (P)	7723-14-0		0.411	mg
Mold Compound-Black	1890.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		132.3	mg
			Supplier	Carbon Black (C)	1333-86-4		18.9	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		661.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		132.3	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		945	mg
Plating	56.4	mg	Supplier	Tin (Sn)	7440-31-5		56.4	mg
Wire Bond - Cu	4.0	mg	Supplier	Palladium (Pd)	7440-05-3		0.08	mg
			Supplier	Copper (Cu)	7440-50-8		3.92	mg